

# LNJ115W8PRA

## Surface Mounting Chip LED

TSS Bi-Color Type

**■ Absolute Maximum Ratings**  $T_a = 25^\circ\text{C}$ 

- Green

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	60	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.**■ Lighting Color / Lens Color**

- Green / White Diffused
- Red / White Diffused

- Red

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	50	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.**■ Electro-Optical Characteristics**  $T_a = 25^\circ\text{C}$ 

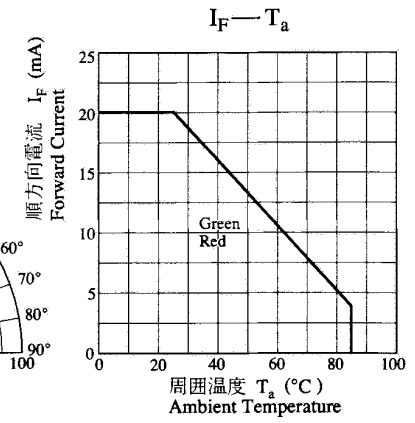
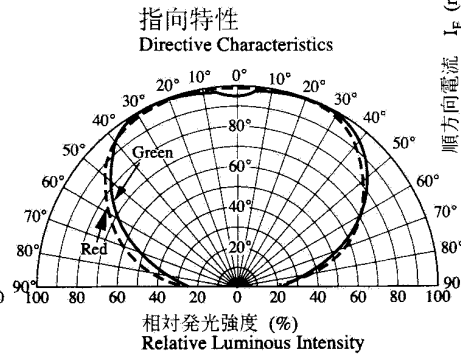
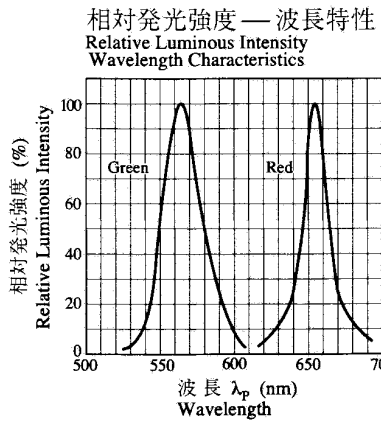
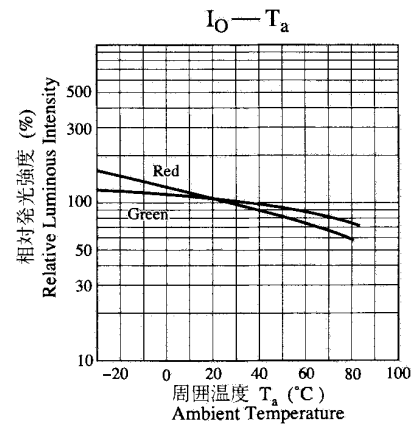
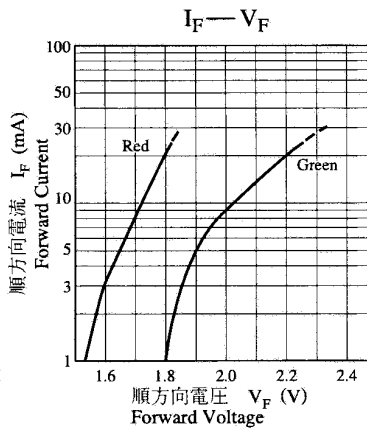
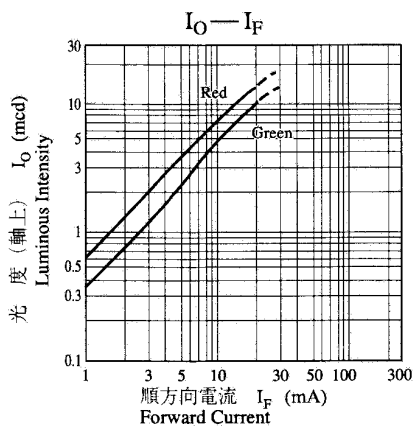
- Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		1.8	5.0	17.7	mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			10	$\mu\text{A}$

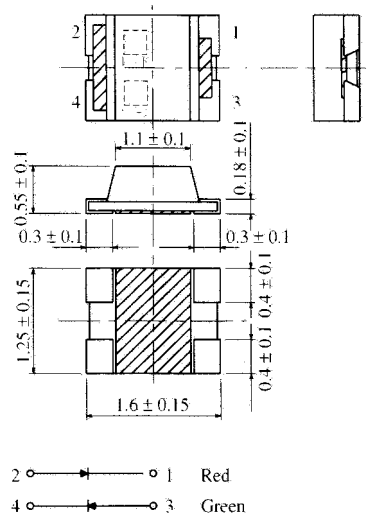
■ Electro-Optical Characteristics (Continued)  $T_a = 25^\circ\text{C}$

• Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		2.2	6.7	18.8	mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.72	2.5	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		655		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm
Reverse current	$I_R$	$V_R = 3\text{ V}$			100	$\mu\text{A}$



■ Package (Unit: mm)



• Pin name

- 1, 4: Cathode
- 2, 3: Anode

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